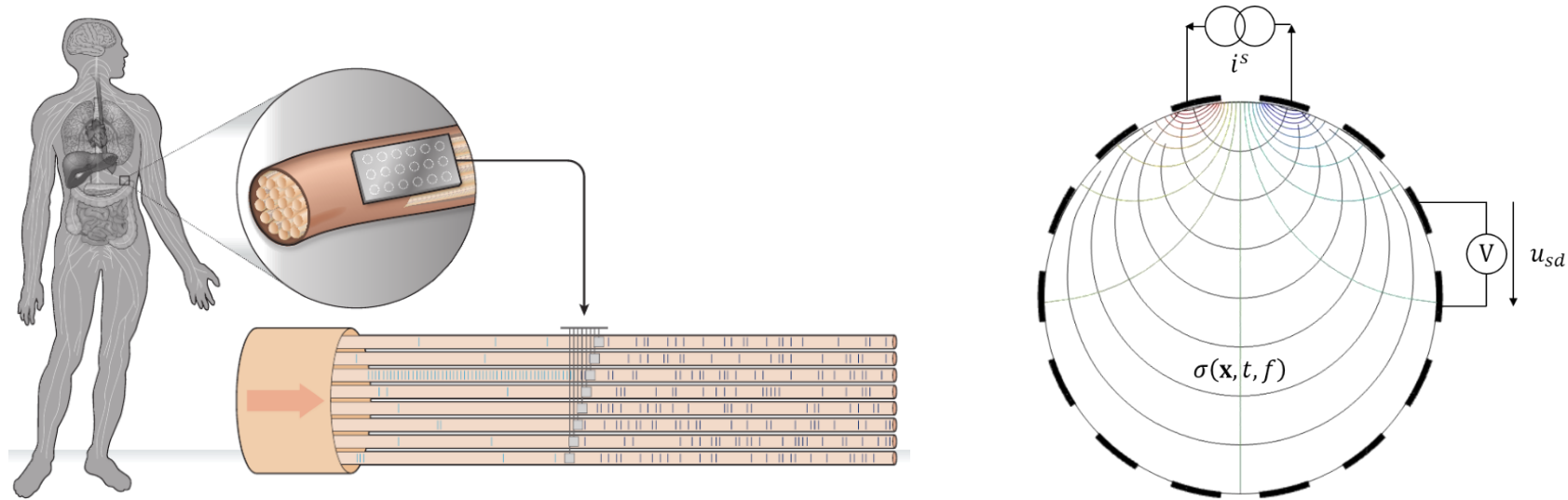


Flexible Numerical Platform For Electrical Impedance Tomography

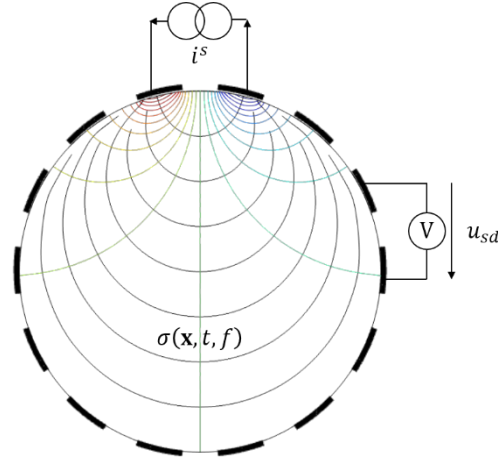


Alexandre Fouchard^{1,2}, Stéphane Bonnet¹, Lionel Hervé¹, Olivier David²

Université Grenoble Alpes, F-38000 Grenoble, France 1. CEA, Leti 2. INSERM, Grenoble Institute of Neurosciences

alexandre.fouchard@centraliens-lyon.net

Signal



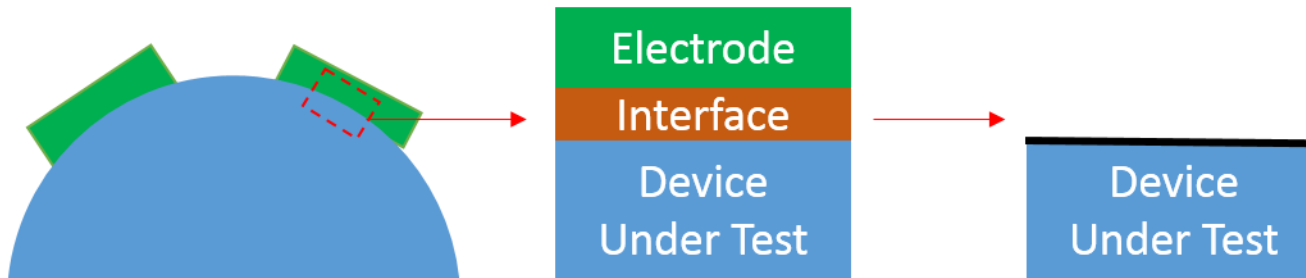
Source – detector transfer impedance

$$Z_{sd} = \frac{u_{sd}}{i^s}$$

- Geometry (boundary shape & size)
- Electrode configuration
- Conductivity distribution $\sigma(\mathbf{x}, t, f)$

Model: Electrode & Interface as a boundary condition

Current injection, potential measurements



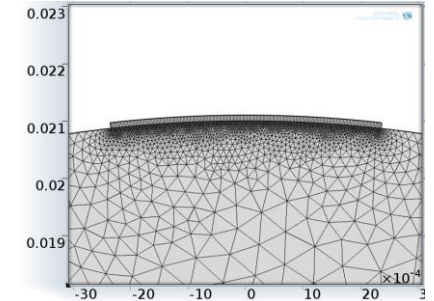
$$\left\{ \begin{array}{l} \nabla \cdot (-\sigma \nabla v) = 0 \quad \forall x \in \Omega \\ v + z_e \sigma \nabla v \cdot \mathbf{n} = v_e \quad \forall x \in E_e \\ \int_{E_e} \sigma \nabla v \cdot \mathbf{n} d\Gamma = i_e \quad \forall e = 1 \dots E \\ \sigma \nabla v \cdot \mathbf{n} = 0 \quad \forall x \in \partial\Omega \setminus \bigcup_{e=1}^E E_e \end{array} \right.$$

How to take into account contact impedances z_e ?

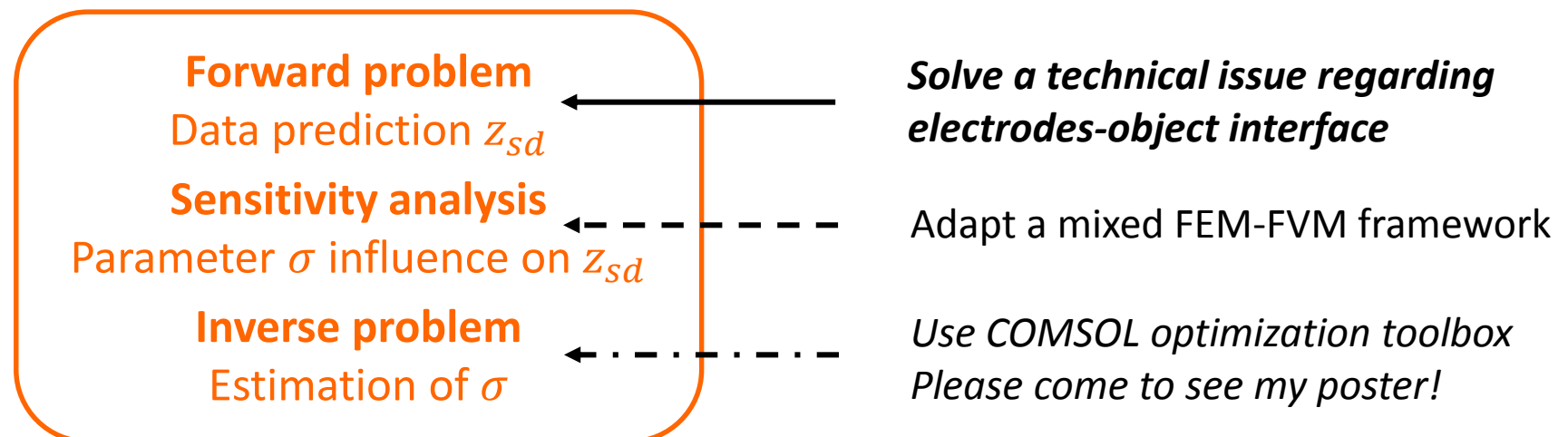
$$z_e / s_e \gg Z_{sd}$$

Literature solutions

1. **Custom-built** FEM-based libraries, e.g. EIDORS
Development & debugging costs, Simplistic computation assumptions, Augmented stiffness matrix
2. Model **electrode thickness** within generalist FEM packages, e.g. COMSOL
*High number of uninformative degrees of freedom
How to recover sensitivity patterns?*



How to perform efficiently EIT modeling using COMSOL ?



Custom-built FEM libraries: specificity of the Complete Electrode Model

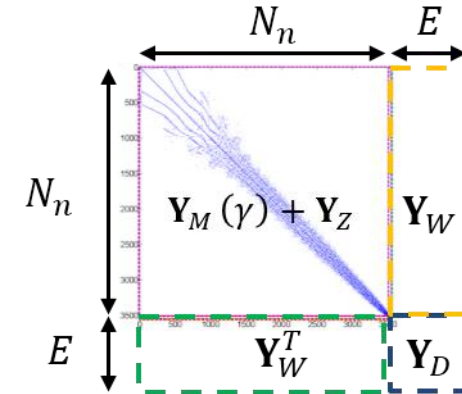
Test functions for electrode potentials along with electric potential discretization

$$-\int_{\Omega} \sigma \nabla v \cdot \nabla w \, d\Omega + \sum_{e=1}^E z_e \int_{E_e} (v - v_e)(w - w_e) \, d\Gamma = \sum_{e=1}^E i_e w_e \quad \forall (w, \mathbf{w}_e)$$

Augmented stiffness matrix

$$\mathbf{Y} \in \mathbb{R}^{(N_n+E) \times (N_n+E)}$$

$$\mathbf{Y} \begin{bmatrix} \mathbf{v}_n \\ \mathbf{v}_e \end{bmatrix} = \begin{bmatrix} \mathbf{Y}_M(\sigma) + \mathbf{Y}_Z & \mathbf{Y}_W \\ \mathbf{Y}_W^T & \mathbf{Y}_D \end{bmatrix} \begin{bmatrix} \mathbf{v}_n \\ \mathbf{v}_e \end{bmatrix} = \begin{bmatrix} \mathbf{0}_{N_n} \\ \mathbf{i}_e \end{bmatrix}$$



COMSOL implementation

CEM as a single Neumann boundary condition

$$-\mathbf{n} \cdot \mathbf{j} = \frac{v_e - v}{z_e}$$

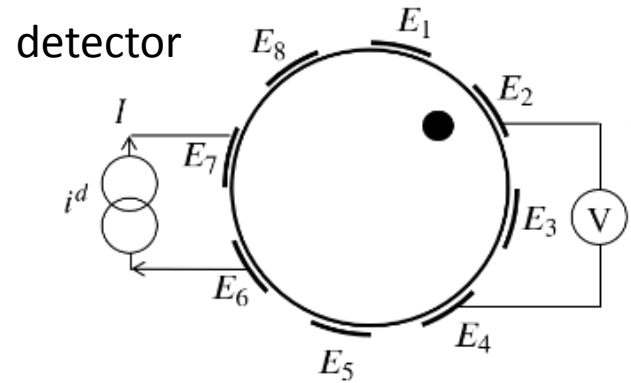
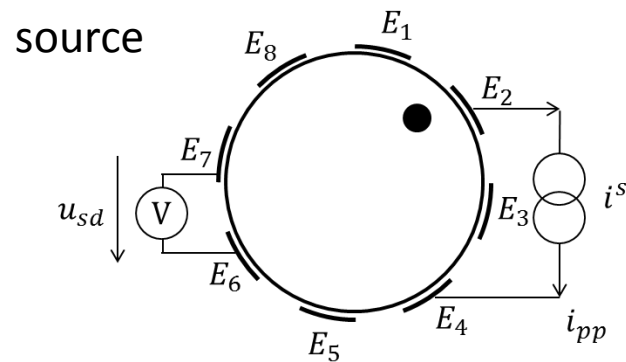
$$v_e = \frac{1}{\|E_e\|} \int_{E_e} v \, d\Gamma + z_e i_e$$

$$-\mathbf{n} \cdot \mathbf{j} = \frac{1}{z_e \|E_e\|} \left(\int_{E_e} v \, d\Gamma + z_e i_e - \|E_e\| v \right)$$

Equivalent formulation with a classic stiffness matrix

electrode potentials deduced during **post-processing**

Dual configurations



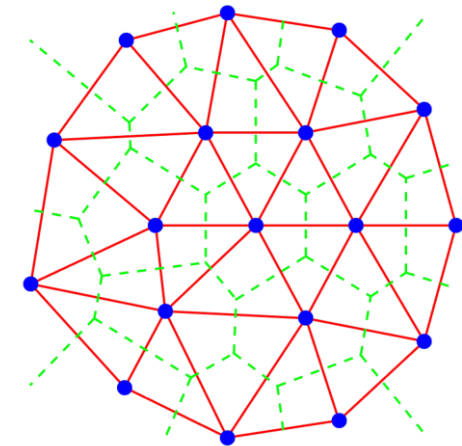
$$\frac{\partial u_{sd}}{\partial \sigma_c} = \frac{-1}{I} \int_{\Omega_c} \nabla v^s \cdot \nabla v^d d\Omega$$

Voronoi cell-based control volumes

(see Fouchard et al. GRETSI 2015)

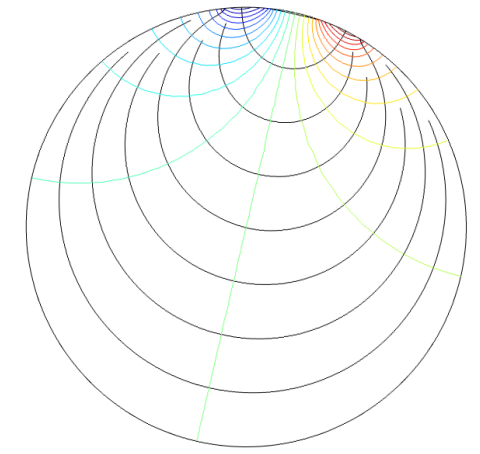
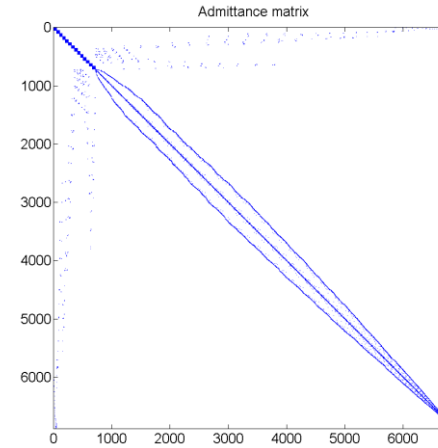
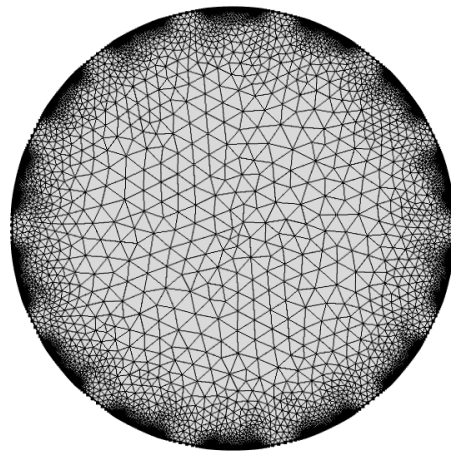
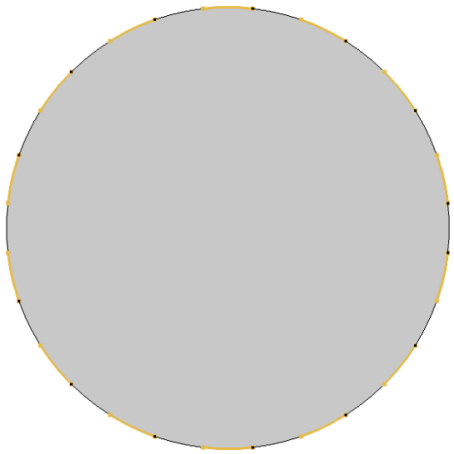
Nodal approximation of electric fields using COMSOL

$$[\mathbf{J}]_{sd,n}^d = \frac{\partial u_{sd}}{\partial \sigma_n} = \frac{-\|\Pi_n\|}{I} \nabla \mathbf{v}_n(i^s) \cdot \nabla \mathbf{v}_n(i^d)$$



Forward solver for EIT: solve identified literature issues towards standardization of numerical tools

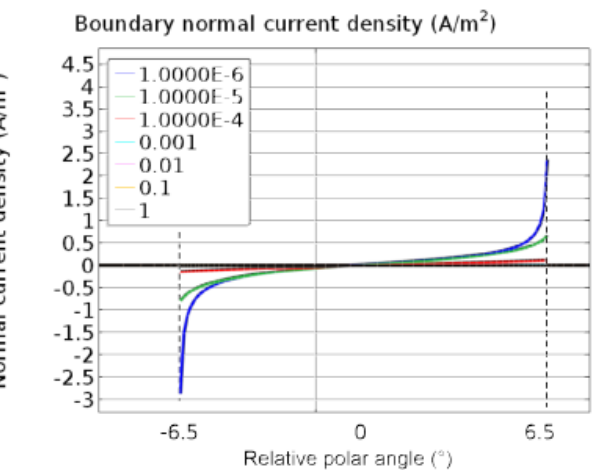
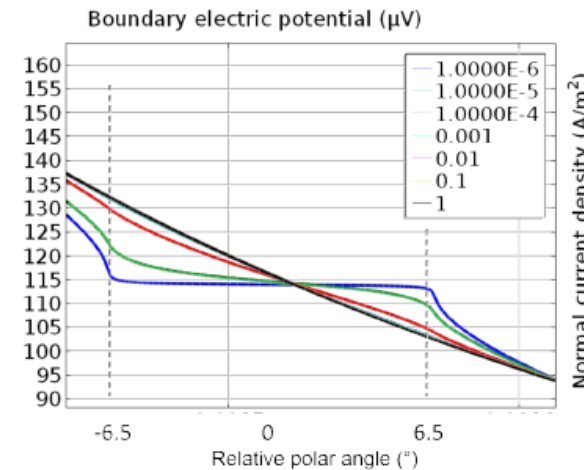
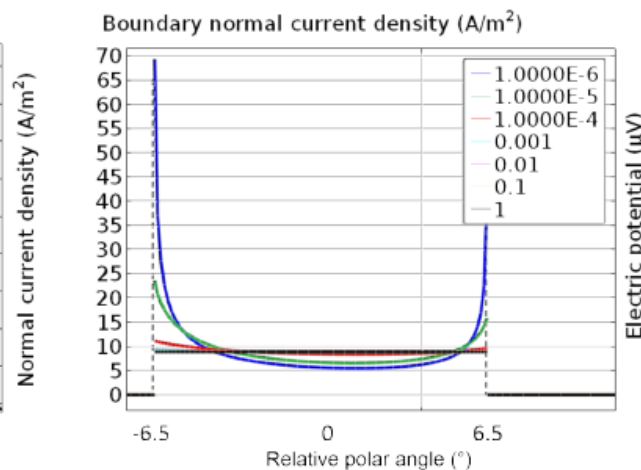
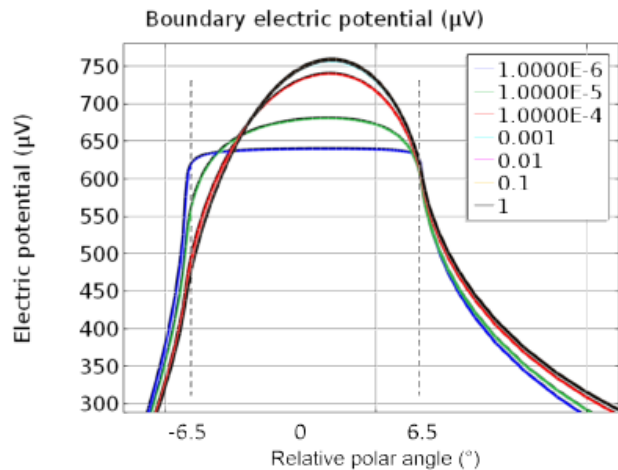
Overall behavior



Influence of electrodes

edge effects with varying contact impedances z_e

strong field modifications in the boundary vicinity



Source electrode

Detector electrode

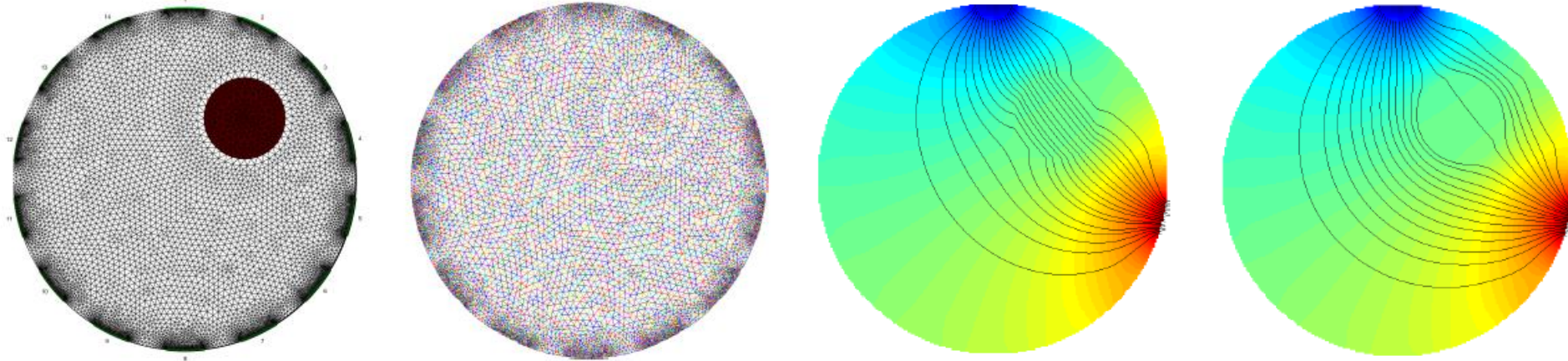
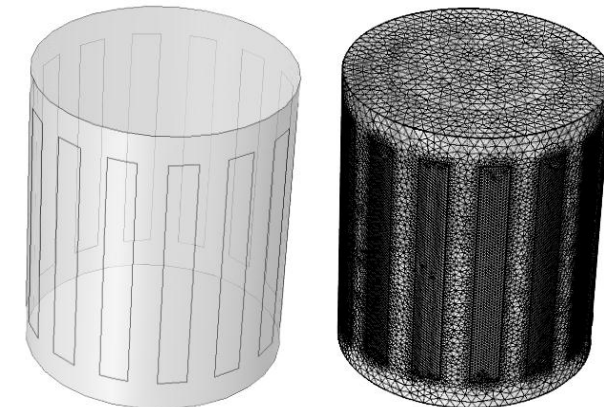


Figure of Merit: maximum of relative error

Results for varying z_e from 10^{-6} to $1 \Omega \cdot m^2$

Test case	FoM Node potentials	FoM Electrode potentials	CPU time (EIDORS / COMSOL) *
2D	10^{-10}	10^{-12}	26 s / 10 s
3D	10^{-4}	10^{-7}	330 s / 550 s



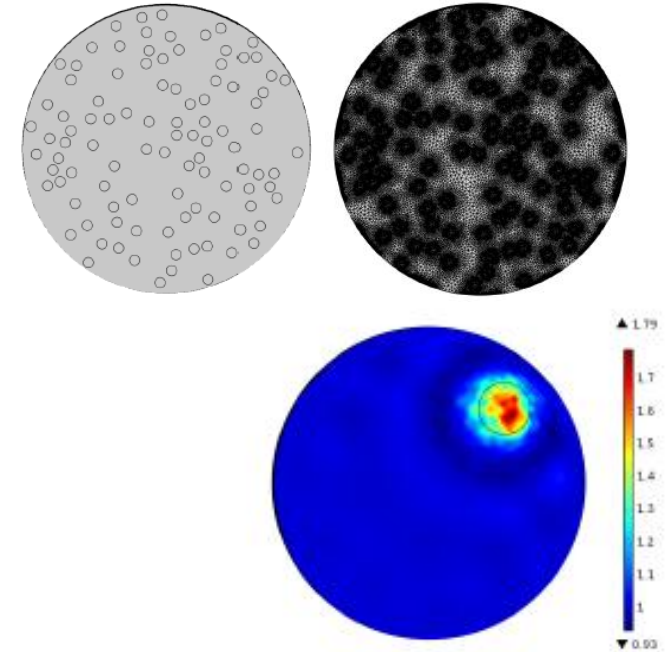
CPU time

EIDORS: assembly of stiffness matrix & solving only
COMSOL: also includes meshing

Versatile forward solver

Electrode
Interface
Device
Under Test

1. **Means of taking into account interface effects** (metallic electrodes)
2. **Consistent numerical approximation** with previous developments
3. **Complete framework for EIT**, with inverse problem capabilities (*poster*)
4. Extensions towards other electromagnetic situations
e.g. tDCS, EEG, DBS (forward & inverse problems)

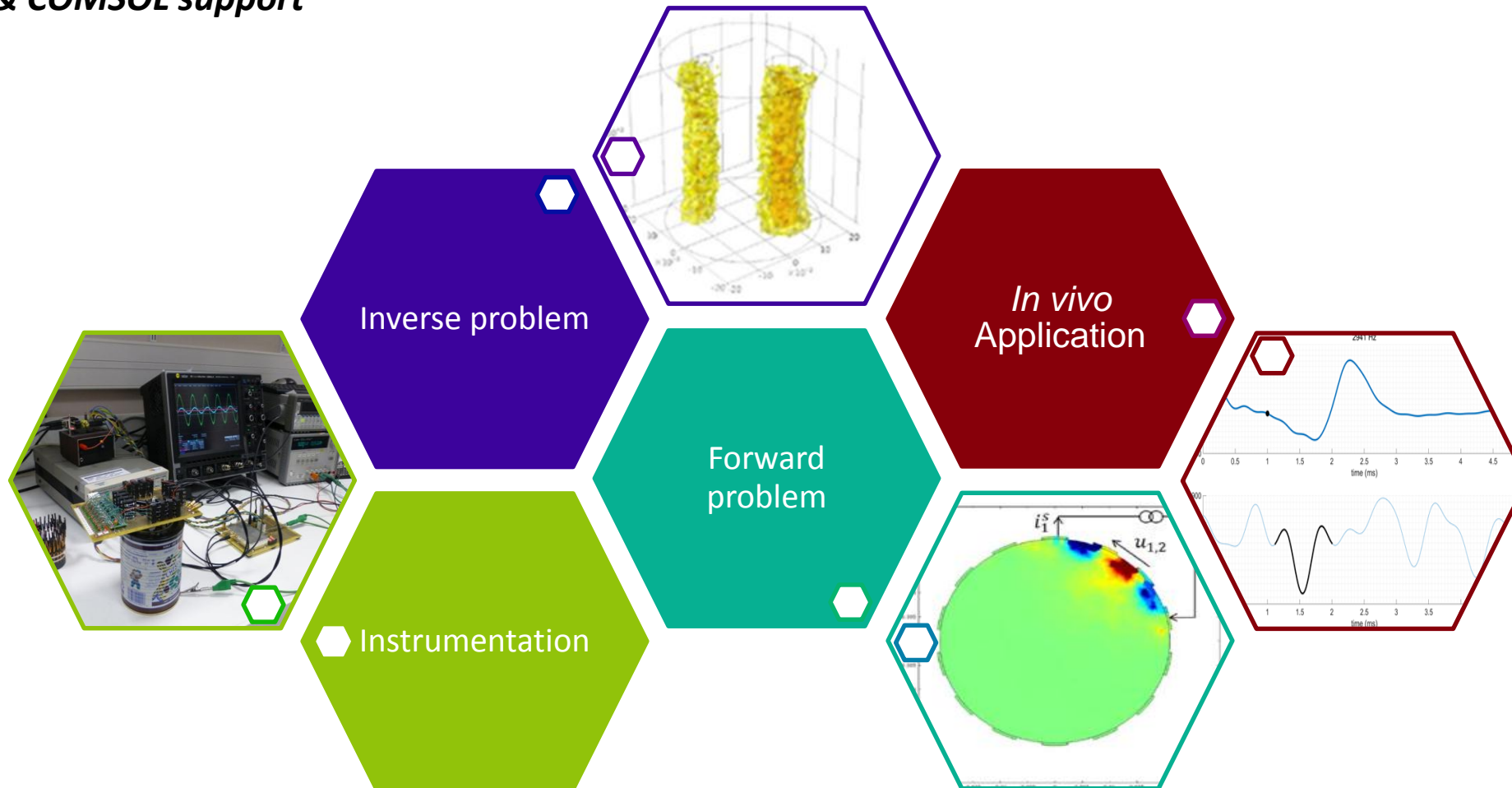


Future developments towards

1. Incorporation of **advanced regularization strategies**
2. **Adaptive** forward / inverse **meshing** schemes
3. Multispectral capabilities
4. Reduce **CPU time** for inverse problems & **3D models**
5. **Multiphysics coupling** for multimodality imaging

**Acknowledge Eric Favre
& COMSOL support**

Please come to see my poster!



Looking for a job 😊, after my defense (Nov 6, 2015)